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FDS5670

60V N-Channel PowerTrench™ MOSFET

General Description

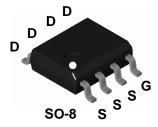
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

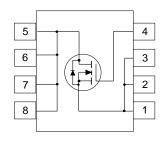
These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{\text{DS}(\text{ON})}$ specifications.

The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

Features

- 10 A, 60 V. $R_{DS(ON)} = 0.014 \Omega$ @ $V_{GS} = 10 V$ $R_{DS(ON)} = 0.017 \Omega$ @ $V_{GS} = 6 V$.
- · Low gate charge.
- · Fast switching speed.
- High performance trench technology for extremely low $R_{\scriptscriptstyle DS(\text{ON})}.$
- · High power and current handling capability.





Absolute Maximum Ratings T_a = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V _{DSS}	Drain-Source Voltage		60	V	
V _{GSS}	Gate-Source Voltage		±20	V	
I _D	Drain Current - Continuous	(Note 1a)	10	А	
	- Pulsed		50	7	
P _D	Power Dissipation for Single Operation	(Note 1a)	2.5	W	
		(Note 1b)	1.2		
		(Note 1c)	1	7	
T _J , T _{stg}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

$R_{_{\theta}JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
R _e JC	Thermal Resistance, Junction-to-Case	(Note 1)	25	°C/W

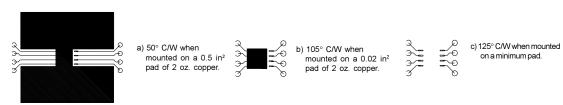
Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity	
FDS5670	FDS5670	13"	12mm	2500 units	

Symbol	Parameter	Test Conditions		Тур	Max	Units
Off Char	acteristics			•	•	•
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$				V
<u>ΔBV_{DSS}</u> ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		58		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 48 V, V _{GS} = 0 V			1	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -20 V, V _{DS} = 0 V			-100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2	2.4	4	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		6.8		mV/°C
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}, T_J = 125^{\circ}\text{C}$ $V_{GS} = 6 \text{ V}, I_D = 9 \text{ A}$		0.012 0.019 0.014	0.014 0.027 0.017	Ω
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 5 V	25			Α
g FS	Forward Transconductance	V _{DS} = 5 V, I _D = 10 A		39		S
Dvnamic	Characteristics					
Ciss	Input Capacitance	V _{DS} = 15 V, V _{GS} = 0 V		2900		pF
Coss	Output Capacitance	f = 1.0 MHz		685		pF
C _{rss}	Reverse Transfer Capacitance			180		pF
Switchin	ng Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 30 V, I _D = 1 A		16	29	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		10	20	ns
t _{d(off)}	Turn-Off Delay Time			50	80	ns
t _f	Turn-Off Fall Time			23	42	ns
Q _g	Total Gate Charge	V _{DS} = 20 V, I _D = 10 A		49	70	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V,		9		nC
Q _{gd}	Gate-Drain Charge			10.4		nC
Drain-So	ource Diode Characteristics and	d Maximum Ratings			-	-
I _S	Maximum Continuous Drain-Source Did	•			2.1	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 2.1 A (Note 2)		0.72	1.2	V

Notes:

R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BJC} is guaranteed by design while R_{BJA} is determined by the user's board design.



Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width $\leq 300~\mu s,~Duty~Cycle \leq 2.0\%$

Typical Characteristics

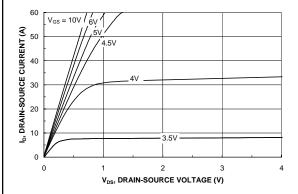


Figure 1. On-Region Characteristics.

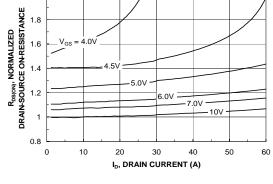


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

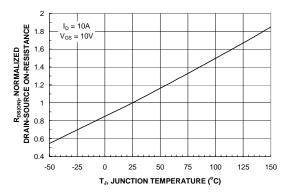


Figure 3. On-Resistance Variation with Temperature.

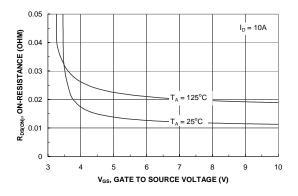


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

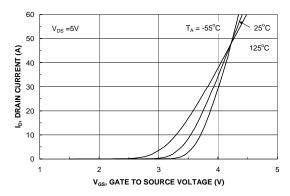


Figure 5. Transfer Characteristics.

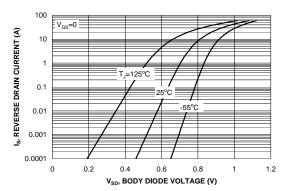
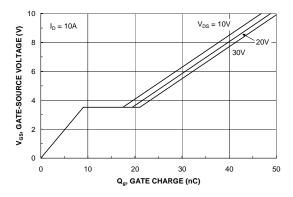


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



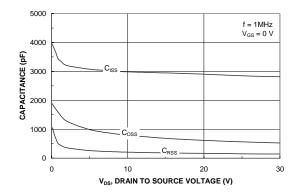
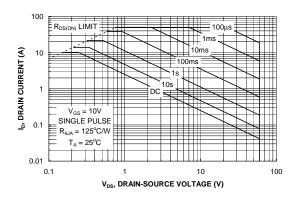


Figure 7. Gate-Charge Characteristics.





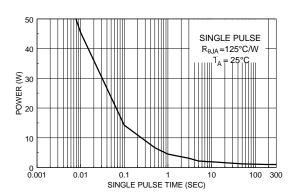


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

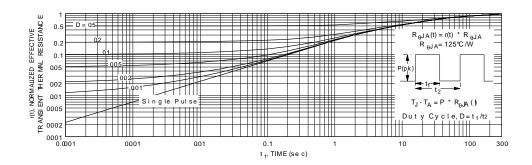


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient themal response will change depending on the circuit board design.

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